



#### P-CHANNEL ENHANCEMENT MODE MOSFET

#### **Product Summary**

| BV <sub>DSS</sub> | Ros(on) Max                    | I <sub>D</sub> Max<br>T <sub>A</sub> = +25°C |
|-------------------|--------------------------------|--|
| 201/              | $30m\Omega$ @ $V_{GS} = -4.5V$ | -6.0A  |
| -20V              | 39mΩ @ V <sub>GS</sub> = -2.5V | -5.5A  |

### **Features and Benefits**

- Low Input Capacitance
- Low On-Resistance
- Fast Switching Speed
- ESD Protected
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMP2036UVTQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

### **Description and Applications**

This MOSFET is designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

- DC-DC converters
- Motor controls
- · Power-management functions
- Analog switches

#### **Mechanical Data**

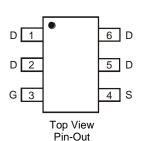
- Package: TSOT26
- Package Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Lead-Frame; Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.013 grams (Approximate)

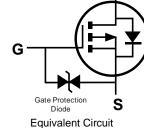






Top View





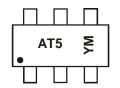
# **Ordering Information** (Note 4)

| Part Number    | Backago | Packing |             |  |
|----------------|---------|---------|-------------|--|
| Fait Number    | Package | Qty.    | Carrier     |  |
| DMP2036UVTQ-7  | TSOT26  | 3,000   | Tape & Reel |  |
| DMP2036UVTQ-13 | TSOT26  | 10,000  | Tape & Reel |  |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# **Marking Information**



AT5 = Product Type Marking Code YM = Date Code Marking Y or  $\overline{Y}$  = Year (ex: K = 2023) M = Month (ex: 9 = September)

#### Date Code Key

| Year  | 2021 | 2022 | 2023 | 2024 | 2025 | 2026 | 2027 | 2028 | 2029 | 2030 | 2031 | 2032 |
|-------|------|------|------|------|------|------|------|------|------|------|------|------|
| Code  | ı    | J    | K    | L    | М    | N    | Р    | R    | S    | T    | U    | V    |
|       |      |      |      |      |      |      |      |      |      |      |      |      |
| Month | Jan  | Feb  | Mar  | Apr  | Мау  | Jun  | Jul  | Aug  | Sep  | Oct  | Nov  | Dec  |



### **Maximum Ratings** (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic  | Symbol       | Value  | Unit            |              |    |
|---|--------------|--|-----------------|--------------|----|
| Drain-Source Voltage                                      |              |  | VDSS            | -20          | V  |
| Gate-Source Voltage                                       |              |  | Vgss            | ±8           | V  |
| Continuous Drain Current (Note 5) V <sub>GS</sub> = -4.5V | Steady State | T <sub>A</sub> = +25°C<br>T <sub>A</sub> = +70°C | ID              | -6.0<br>-5.0 | А  |
| Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%         | )            |  | I <sub>DM</sub> | -40          | Α  |
| Continuous Source-Drain Diode Current (Note 5)            |              |  | Is              | -2,2         | Α  |
| Avalanche Current (Note 6) L = 0.1mH                      |              |  | las             | -21          | Α  |
| Avalanche Energy (Note 6) L = 0.1mH                       |              |  | E <sub>AS</sub> | 23           | mJ |

# Thermal Characteristics (@ TA = +25°C, unless otherwise specified.)

| Characteristic                                   |                        | Symbol           | Value       | Unit |
|--|------------------------|------------------|-------------|------|
| Total Power Discipation (Note 7)                 | T <sub>A</sub> = +25°C | D-               | 1.1         | W    |
| Total Power Dissipation (Note 7)                 | $T_A = +70$ °C         | PD               | 0.7         | VV   |
| Thermal Resistance, Junction to Ambient (Note 7) | Steady State           | Reja             | 108         | °C/W |
| Total Dower Discipation (Note 5)                 | T <sub>A</sub> = +25°C | D-               | 1.5         | W    |
| Total Power Dissipation (Note 5)                 | T <sub>A</sub> = +70°C | PD               | 1.0         | VV   |
| Thermal Resistance, Junction to Ambient (Note 5) | Steady State           | R <sub>θJA</sub> | 81          | °C/W |
| Thermal Resistance, Junction to Case (Note 5)    | Rejc                   | 16               | C/VV        |      |
| Operating and Storage Temperature Range          |                        | TJ, TSTG         | -55 to +150 | °C   |

### Electrical Characteristics (@ TA = +25°C, unless otherwise specified.)

| Characteristic   | Symbol              | Min  | Тур   | Max  | Unit | Test Condition                                   |  |
|--|---------------------|------|-------|------|------|--|--|
| OFF CHARACTERISTICS (Note 8)                           |                     |      |       |      |      |  |  |
| Drain-Source Breakdown Voltage                         | BV <sub>DSS</sub>   | -20  | _     | _    | V    | V <sub>G</sub> S = 0V, I <sub>D</sub> = -250µA   |  |
| Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C | IDSS                | _    | _     | -1   | μΑ   | V <sub>DS</sub> = -16V, V <sub>GS</sub> = 0V     |  |
| Gate-Source Leakage                                    | Igss                | _    | _     | ±10  | μΑ   | $V_{GS} = \pm 8V$ , $V_{DS} = 0V$                |  |
| ON CHARACTERISTICS (Note 8)                            |                     |      |       |      |      | •  |  |
| Gate Threshold Voltage                                 | V <sub>GS(TH)</sub> | -0.4 | _     | -1.0 | V    | $V_{DS} = V_{GS}, I_{D} = -250 \mu A$            |  |
|  |                     |      | 24    | 30   |      | V <sub>G</sub> S = -4.5V, I <sub>D</sub> = -6.4A |  |
| Static Drain-Source On-Resistance                      | RDS(ON)             | _    | 31    | 39   | mΩ   | V <sub>G</sub> S = -2.5V, I <sub>D</sub> = -4.8A |  |
|  |                     |      | 41    | 58   |      | V <sub>G</sub> S = -1.8V, I <sub>D</sub> = -2.5A |  |
| Diode Forward Voltage                                  | V <sub>SD</sub>     | _    | -0.7  | -1.2 | V    | V <sub>GS</sub> = 0V, I <sub>S</sub> = -1.0A     |  |
| DYNAMIC CHARACTERISTICS (Note 9)                       |                     |      |       |      | •    |  |  |
| Input Capacitance                                      | Ciss                | _    | 1,808 | _    |      |  |  |
| Output Capacitance                                     | Coss                | _    | 155   | _    | pF   | $V_{DS} = -15V, V_{GS} = 0V$<br>f = 1.0MHz       |  |
| Reverse Transfer Capacitance                           | C <sub>rss</sub>    | _    | 117   | _    |      | 1 = 1.0lvii iz                                   |  |
| Gate Resistance  | Rg                  | _    | 32    | _    | Ω    | $V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$       |  |
| Total Gate Charge (VGS = -4.5V)                        | Qg                  | _    | 20.5  | _    |      |  |  |
| Gate-Source Charge                                     | Q <sub>gs</sub>     | _    | 2.8   | _    | nC   | $V_{DS} = -10V, V_{GS} = -4.5V$ $I_{D} = -4.0A$  |  |
| Gate-Drain Charge                                      | Qgd                 | _    | 4.1   | _    |      | ID = -4.0A                                       |  |
| Turn-On Delay Time                                     | t <sub>D(ON)</sub>  | _    | 9.1   | _    |      |  |  |
| Turn-On Rise Time                                      | t <sub>R</sub>      | _    | 12.3  | _    |      | V <sub>DS</sub> = -10V, V <sub>GS</sub> = -4.5V  |  |
| Turn-Off Delay Time                                    | t <sub>D(OFF)</sub> | _    | 120   | _    | ns   | $R_g = 6\Omega$ , $I_D = -1.0A$                  |  |
| Turn-Off Fall Time                                     | tF                  | _    | 54    | _    |      |  |  |
| Reverse Recovery Time                                  | trr                 | _    | 23.1  | _    | ns   | I <sub>F</sub> = -1.0A, dI/dt = 100A/μs          |  |
| Reverse Recovery Charge                                | Q <sub>RR</sub>     | _    | 8.3   | _    | nC   | I <sub>F</sub> = -1.0A, dI/dt = 100A/μs          |  |

Notes:

- Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.
   I<sub>AS</sub> and E<sub>AS</sub> ratings are based on low frequency and duty cycles to keep T<sub>J</sub> = +25°C.
   Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
   Short duration pulse test used to minimize self-heating effect.
   Guaranteed by design. Not subject to product testing.



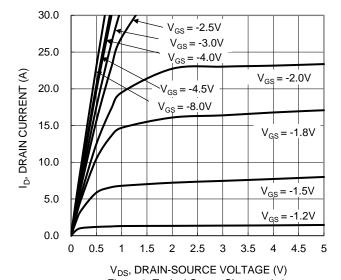


Figure 1. Typical Output Characteristic 150

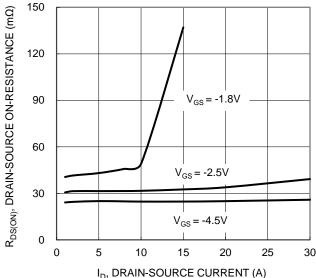


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

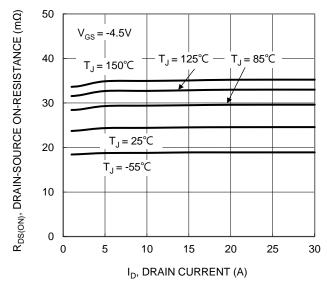


Figure 5. Typical On-Resistance vs. Drain Current and **Temperature** 

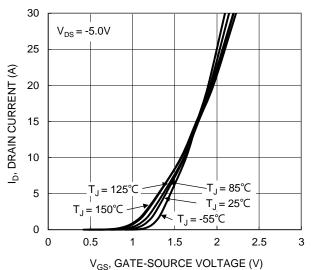


Figure 2. Typical Transfer Characteristic

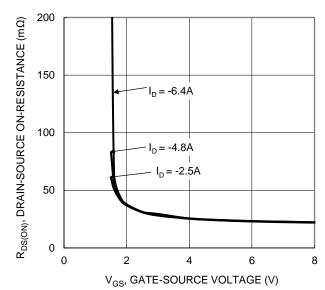


Figure 4. Typical Transfer Characteristic

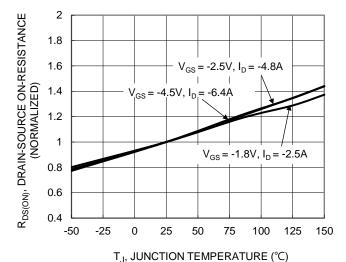


Figure 6. On-Resistance Variation with Temperature





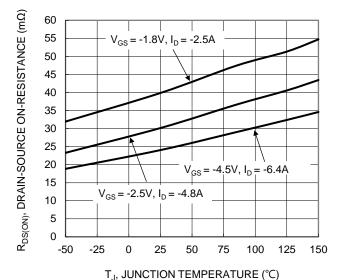
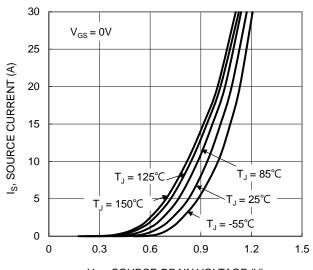
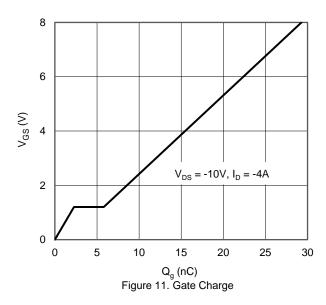
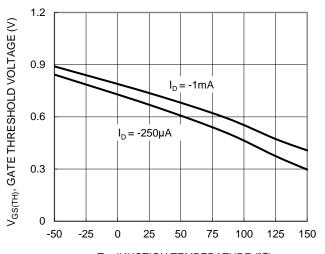


Figure 7. On-Resistance Variation with Temperature



V<sub>SD</sub>, SOURCE-DRAIN VOLTAGE (V) Figure 9. Diode Forward Voltage vs. Current





 $T_J$ , JUNCTION TEMPERATURE (°C) Figure 8. Gate Threshold Variation vs. Junction Temperature

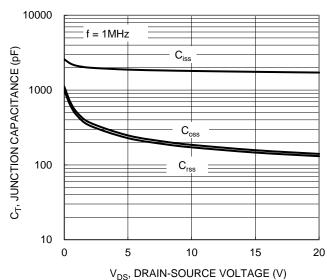
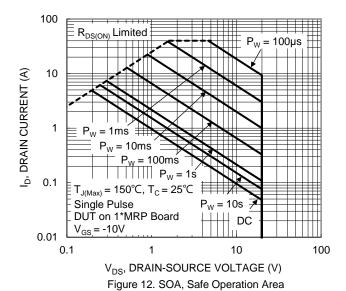


Figure 10. Typical Junction Capacitance





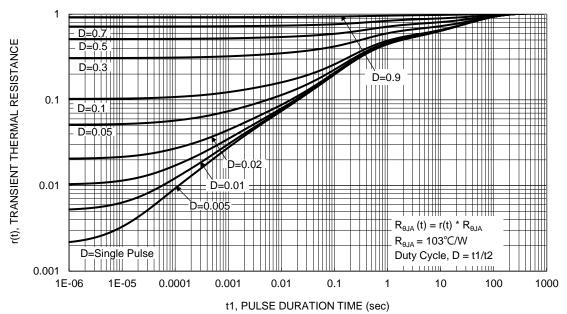


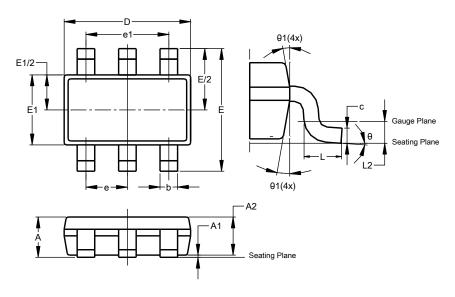
Figure 13. Transient Thermal Resistance



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### TSOT26

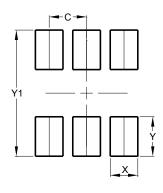


|                      | то        | OT00  |       |  |  |  |  |  |
|----------------------|-----------|-------|-------|--|--|--|--|--|
| TSOT26               |           |       |       |  |  |  |  |  |
| Dim                  | Min       | Max   | Тур   |  |  |  |  |  |
| Α                    | -         | 1.00  | -     |  |  |  |  |  |
| <b>A1</b>            | 0.010     | 0.100 | -     |  |  |  |  |  |
| A2                   | 0.840     | 0.900 | -     |  |  |  |  |  |
| D                    | 2.800     | 3.000 | 2.900 |  |  |  |  |  |
| Ε                    | 2.800 BSC |       |       |  |  |  |  |  |
| E1                   | 1.500     | 1.700 | 1.600 |  |  |  |  |  |
| b                    | 0.300     | 0.450 | -     |  |  |  |  |  |
| С                    | 0.120     | 0.200 | _     |  |  |  |  |  |
| е                    | 0.950 BSC |       |       |  |  |  |  |  |
| e1                   | 1.900 BSC |       |       |  |  |  |  |  |
| L                    | 0.30      | -     |       |  |  |  |  |  |
| L2                   | 0.250 BSC |       |       |  |  |  |  |  |
| θ                    | 0°        | 8°    | 4°    |  |  |  |  |  |
| θ1                   | 4°        | 12°   | -     |  |  |  |  |  |
| All Dimensions in mm |           |       |       |  |  |  |  |  |

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### TSOT26



| Dimensions | Value (in mm) |
|------------|---------------|
| С          | 0.950         |
| Х          | 0.700         |
| Y          | 1.000         |
| V1         | 2 200         |



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